

Data sheet acquired from Harris Semiconductor SCHS136

*CD74HC85, CD74HCT85* 

High Speed CMOS Logic 4-Bit Magnitude Comparator

August 1997

#### **Features**

- · Buffered Inputs and Outputs
- Typical Propagation Delay: 13ns (Data to Output at V<sub>CC</sub> = 5V, C<sub>L</sub> = 15pF, T<sub>A</sub> = 25°C
- Serial or Parallel Expansion Without External Gating
- Fanout (Over Temperature Range)
- Bus Driver Outputs ........... 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL}$  = 30%,  $N_{IH}$  = 30% of  $V_{CC}$  at  $V_{CC}$  = 5V
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,
    V<sub>IL</sub>= 0.8V (Max), V<sub>IH</sub> = 2V (Min)
  - CMOS Input Compatibility, I<sub>I</sub>  $\leq$  1 $\mu$ A at V<sub>OL</sub>, V<sub>OH</sub>

### Description

The CD74HC85 and CD74HCT85 are high speed magnitude comparators that use silicon-gate CMOS technology to achieve operating speeds similar to LSTTL with the low power consumption of standard CMOS integrated circuits.

These 4-bit devices compare two binary, BCD, or other monotonic codes and present the three possible magnitude results at the outputs (A > B, A < B, and A = B). The 4-bit input words are weighted (A0 to A3 and B0 to B3), where A3 and  $B_3$  are the most significant bits.

The devices are expandable without external gating, in both serial and parallel fashion. The upper part of the truth table indicates operation using a single device or devices in a serially expanded application. The parallel expansion scheme is described by the last three entries in the truth table

### **Ordering Information**

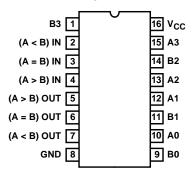
PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC85E	-55 to 125	16 Ld PDIP	E16.3
CD74HCT85E	-55 to 125	16 Ld PDIP	E16.3
CD74HC85M	-55 to 125	16 Ld SOIC	M16.15
CD74HCT85M	-55 to 125	16 Ld SOIC	M16.15

#### NOTES:

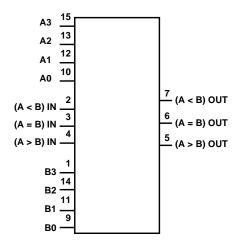
- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- Die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

#### Pinout

#### CD74HC85, CD74HCT85 (PDIP, SOIC) TOP VIEW



# Functional Diagram



### TRUTH TABLE

COMPARING INPUTS				CAS	CADING IN	PUTS	OUTPUTS				
A3, B3	A2, B2	A1, B1	A0, B0	A > B	A < B	A = B	A > B	A < B	A = B		
SINGLE DEVIC	E OR SERIES C	ASCADING									
A3 > B3	Х	Х	Х	Х	Х	х	Н	L	L		
A3 < B3	Х	Х	Х	Х	Х	Х	L	Н	L		
A3 = B3	A2 >B2	Х	Х	Х	Х	Х	Н	L	L		
A3 = B3	A2 < B2	Х	Х	Х	Х	Х	L	Н	L		
A3 = B3	A2 = B2	A1 > B1	Х	Х	Х	Х	Н	L	L		
A3 = B3	A2 = B2	A1 < B1	Х	Х	Х	Х	L	Н	L		
A3 = B3	A2 = B2	A1 = B1	A0 > B0	Х	Х	Х	Н	L	L		
A3 = B3	A2 = B2	A1 = B1	A0 < B0	Х	Х	Х	L	Н	L		
A3 = B3	A2 = B2	A1 = B1	A0 = B0	Н	L	L	Н	L	L		
A3 = B3	A2 = B2	A1 = B1	A0 = B0	L	Н	L	L	Н	L		
A3 = B3	A2 = B2	A1 = B1	A0 = B0	L	L	Н	L	L	Н		
PARALLEL CA	ASCADING			•		-	-				
A3 = B3	A2 = B2	A1 = B1	A0 = B0	Х	Х	Н	L	L	Н		
A3 = B3	A2 = B2	A1 = B1	A0 = B0	Н	Н	L	L	L	L		
A3 = B3	A2 = B2S	A1 = B1	A0 = B0	L	L	L	Н	Н	L		

NOTE: H = High Voltage Level, L = Low Voltage, Level, X = Don't Care

## **Absolute Maximum Ratings**

DC Supply Voltage, V <sub>CC</sub> 0.5V to 7V
DC Input Diode Current, I <sub>IK</sub>
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$
DC Output Diode Current, I <sub>OK</sub>
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$
DC V <sub>CC</sub> or Ground Current, I <sub>CC or</sub> I <sub>GND</sub>

#### **Thermal Information**

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ (oC/W)
PDIP Package	90
SOIC Package	190
Maximum Junction Temperature	150 <sup>0</sup> C
Maximum Storage Temperature Range	65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300 <sup>o</sup> C
(SOIC - Lead Tips Only)	

## **Operating Conditions**

Temperature Range (T <sub>A</sub> )55°C to 125°C
Supply Voltage Range, V <sub>CC</sub>
HC Types2V to 6V
HCT Types
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub>
Input Rise and Fall Time
2V
4.5V 500ns (Max)
6V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

3.  $\theta_{\mbox{\scriptsize JA}}$  is measured with the component mounted on an evaluation PC board in free air.

## **DC Electrical Specifications**

		TES CONDIT		V <sub>CC</sub> 25°C				-40°C 1	O 85°C	-55°C T		
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	) (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES						-						
High Level Input	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V
Voltage				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	V
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output	VoH	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
Voltage CMOS Loads			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
CIVIOS LUaus			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output	7		-	-	-	-	-	-	-	-	-	V
Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
TTE LOads			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
Voltage CMOS Loads			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
CIVIOS LUaus			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	μΑ
Quiescent Device Current	Icc	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	μΑ

## DC Electrical Specifications (Continued)

		TEST CONDITIONS		Vcc	25°C			-40°C 1	O 85°C	-55°C T				
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS		
HCT TYPES														
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V		
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V		
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V		
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V		
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V		
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V		
Input Leakage Current	ΙΙ	V <sub>CC</sub> and GND	0	5.5	-		±0.1	-	±1	-	±1	μΑ		
Quiescent Device Current	Icc	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μΑ		
Additional Quiescent Device Current Per Input Pin: 1 Unit Load (Note)	Δl <sub>CC</sub>	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μА		

NOTE: For dual-supply systems theorectical worst case ( $V_I = 2.4V$ ,  $V_{CC} = 5.5V$ ) specification is 1.8mA.

## **HCT Input Loading Table**

INPUT	UNIT LOADS
A0-A3, B0-B3 and (A = B) IN	1.5
(A > B) IN, (A < B) IN	1

NOTE: Unit Load is  $\Delta I_{CC}$  limit specified in DC Electrical Table, e.g. 360 $\mu$ A max at 25 $^{o}$ C.

## Switching Specifications Input $t_r$ , $t_f = 6ns$

		TEST		25°C			-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	V <sub>CC</sub> (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES			-			-				-	
Propagation Delay,	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	195	-	245	-	295	ns
$A_n$ , $B_n$ to $(A > B)$ OUT, (A < B) OUT			4.5	-	-	39	-	47	-	59	ns
(A < B) 001		C <sub>L</sub> = 15pF	5	-	16	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	33	-	42	-	50	ns
$A_n$ , $B_n$ to $(A = B)$ OUT	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	175	-	240	-	265	ns
			4.5	-	-	35	-	44	-	53	ns
		C <sub>L</sub> = 15pF	5	-	14	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	30	-	37	-	45	ns

## Switching Specifications Input $t_r$ , $t_f$ = 6ns (Continued)

		TEST		25°C			-40°C TO 85°C		-55°C TO 125°C			
PARAMETER	SYMBOL	CONDITIONS	V <sub>CC</sub> (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS	
(A > B) IN, (A < B) IN, (A = B) IN	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	140	-	175	-	210	ns	
to (A > B) OUT, (A < B) OUT			4.5	-	-	28	-	35	-	42	ns	
		C <sub>L</sub> = 15pF	5	-	11	-	-	-	-	-	ns	
		C <sub>L</sub> = 50pF	6	-	-	24	-	30	-	36	ns	
(A > B) IN to (A = B) OUT	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	120	-	150	-	180	ns	
			4.5	-	-	24	-	30	-	36	ns	
		C <sub>L</sub> = 15pF	5	-	9	-	-	-	-	-	ns	
		C <sub>L</sub> = 50pF	6	-	-	20	-	26	-	31	ns	
Power Dissipation Capacitance (Notes 2, 3)	C <sub>PD</sub>	-	5	-	24	-	-	-	-	-	pF	
Output Transition Times	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns	
(Figure 1)			4.5	-	-	15	-	19	-	22	ns	
			6	-	-	13	-	16	-	19	ns	
Input Capacitance	C <sub>IN</sub>	-	-	-	-	10	-	10	-	10	pF	
HCT TYPES												
Propagation Delay,	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	37	-	46	-	56	ns	
An, Bn to (A > B) OUT, (A < B) OUT		C <sub>L</sub> = 15pF	5	1	15	-	-	i	ı	-	ns	
An, Bn to $(A = B)$ OUT	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	40	-	50	-	60	ns	
		C <sub>L</sub> = 15pF	5	-	17	-	-	-	-	-	ns	
(A > B) IN, (A < B) IN, (A = B) IN	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	30	-	38	-	45	ns	
to $(A > B)$ OUT, $(A < B)$ OUT		C <sub>L</sub> = 15pF	5	-	12	-	-	-	-	-	ns	
(A > B) IN to (A = B) OUT	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	31	-	39	-	47	ns	
		C <sub>L</sub> = 15pF	5	-	13	-	-	-	-	-	ns	
Output Transition Times (Figure 1)	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	15	-	19	-	22	ns	
Power Dissipation Capacitance (Notes 4, 5)	C <sub>PD</sub>	-	5	-	26	-	-	-	-	-	pF	
Input Capacitance	C <sub>IN</sub>	-	-	-	-	10	-	10	-	10	pF	

#### NOTES:

- 4.  $C_{\mbox{PD}}$  is used to determine the dynamic power consumption, per gate/package.
- 5.  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

### Test Circuits and Waveforms

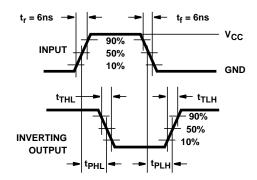


FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGA-TION DELAY TIMES, COMBINATION LOGIC

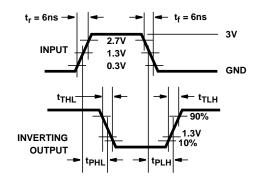
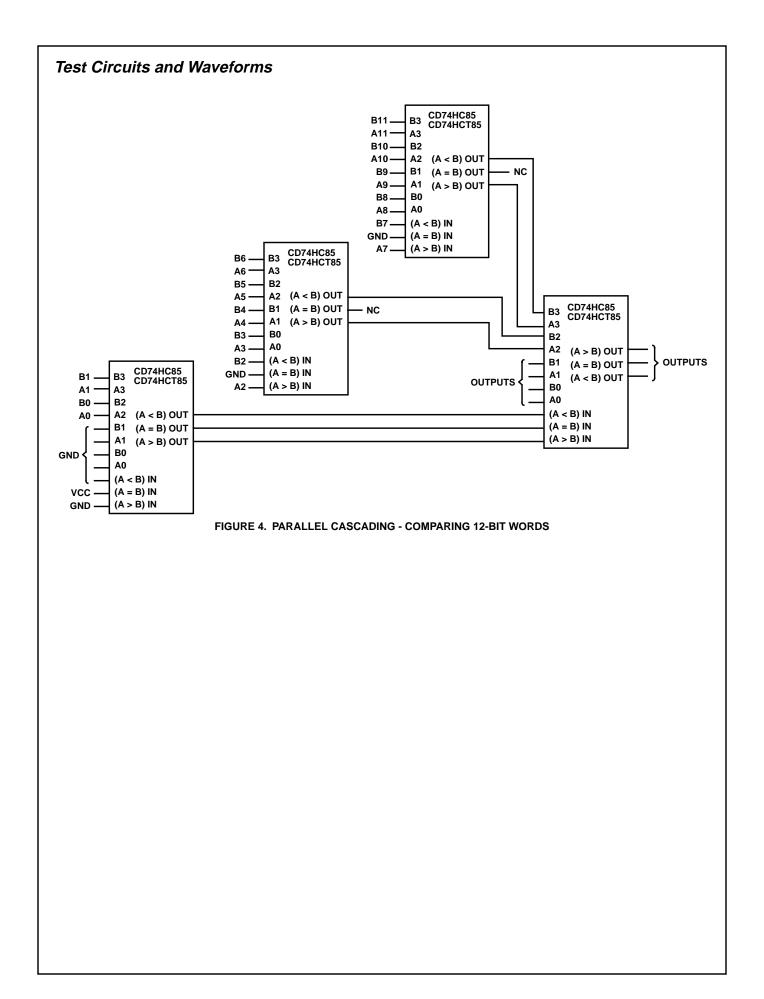


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

#### Test Circuits and Waveforms GND · (A > B) IN (A = B) IN $v_{cc}$ (A < B) IN GND A0 A0 Α1 A1 A2 CD74HC85 CD74HCT85 A2 -LEAST SIGNIFICANT 4-BITS OF EACH WORD А3 -А3 B0 B0 -B1 **–** В1 (A > B) IN B2 -B2 (A = B) IN В3 В3 (A < B) IN Α4 A5 CD74HC85 A6 CD74HCT85 Α5 A6 · Α7 Α7 В4 B4 -B5 (A > B) OUT B5 · (A > B) IN **B6 (A = B) OUT** В6-(A = B) IN B7 (A < B) OUT B7 -(A < B) IN A0 A1 CD74HC85 A2 CD74HCT85 A2 MOST SIGNIFICANT 4-BITS OF EACH WORD А3 -А3 В0 -B0 B1 (A > B) OUT B1 OUTPUTS В2 B2 (A = B) OUT B3 (A < B) OUT В3 -

FIGURE 3. SERIES CASCADING - COMPARING 12-BIT WORDS



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